
OHCI-Lynx™ PCI-Based IEEE 1394 Host Controller

FEATURES

- 3.3-V and 5-V PCI bus signaling
- 3.3-V supply (core voltage is internally regulated to 1.8 V)
- Serial bus data rates of 100M bits/s, 200M bits/s, and 400M bits/s
- Physical write posting of up to three outstanding transactions
- Serial ROM interface supports 2-wire devices
- External cycle timer control for customized synchronization
- PCI burst transfers and deep FIFOs to tolerate large host latency
- Two general-purpose I/Os
- Fabricated in advanced low-power CMOS process
- Packaged in 100-terminal LQFP (PZT)
- `PCI_CLKRUN` protocol

DESCRIPTION

The Texas Instruments TSB12LV26 device is a PCI-to-1394 host controller compliant with the *PCI Local Bus Specification*, *PCI Bus Power Management Interface Specification*, IEEE Std 1394-1995, and *1394 Open Host Controller Interface Specification*. The chip provides the IEEE 1394 link function and is compatible with 100M bits/s, 200M bits/s, and 400M bits/s serial bus data rates.

As required by the *1394 Open Host Controller Interface Specification* (OHCI) and IEEE Std 1394a-2000, internal control registers are memory-mapped and nonprefetchable. The PCI configuration header is accessed through configuration cycles specified by PCI and provides plug-and-play (PnP) compatibility. Furthermore, the TSB12LV26 device is compliant with the *PCI Bus Power Management Interface Specification*, per the *PC 99 Design Guide* requirements. TSB12LV26 device supports the D0, D2, and D3 power states.

The TSB12LV26 design provides PCI bus master bursting and is capable of transferring a cacheline of data at 132M bytes/s after connection to the memory controller. Since PCI latency can be large, deep FIFOs are provided to buffer 1394 data.

The TSB12LV26 device provides physical write posting buffers and a highly-tuned physical data path for SBP-2 performance. The TSB12LV26 device also provides multiple isochronous contexts, multiple cacheline burst transfers, advanced internal arbitration, and bus-holding buffers on the PHY/link interface.

An advanced CMOS process achieves low power consumption and allows the TSB12LV26 device to operate at PCI clock rates up to 33 MHz.

NOTE:

This product is for high-volume PC applications only. For a complete datasheet or more information contact support@ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

OHCI-Lynx is a trademark of Texas Instruments.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TSB12LV26PZT	Active	Production	TQFP (PZT) 100	90 JEDEC TRAY (10+1)	Yes	NIPDAU	Level-4-260C-72 HR	0 to 70	TSB12LV26 F731652A
TSB12LV26PZT.A	Active	Production	TQFP (PZT) 100	90 JEDEC TRAY (10+1)	Yes	NIPDAU	Level-4-260C-72 HR	0 to 70	TSB12LV26 F731652A

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TSB12LV26 :

- Enhanced Product : [TSB12LV26-EP](#)

NOTE: Qualified Version Definitions:

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TRAY



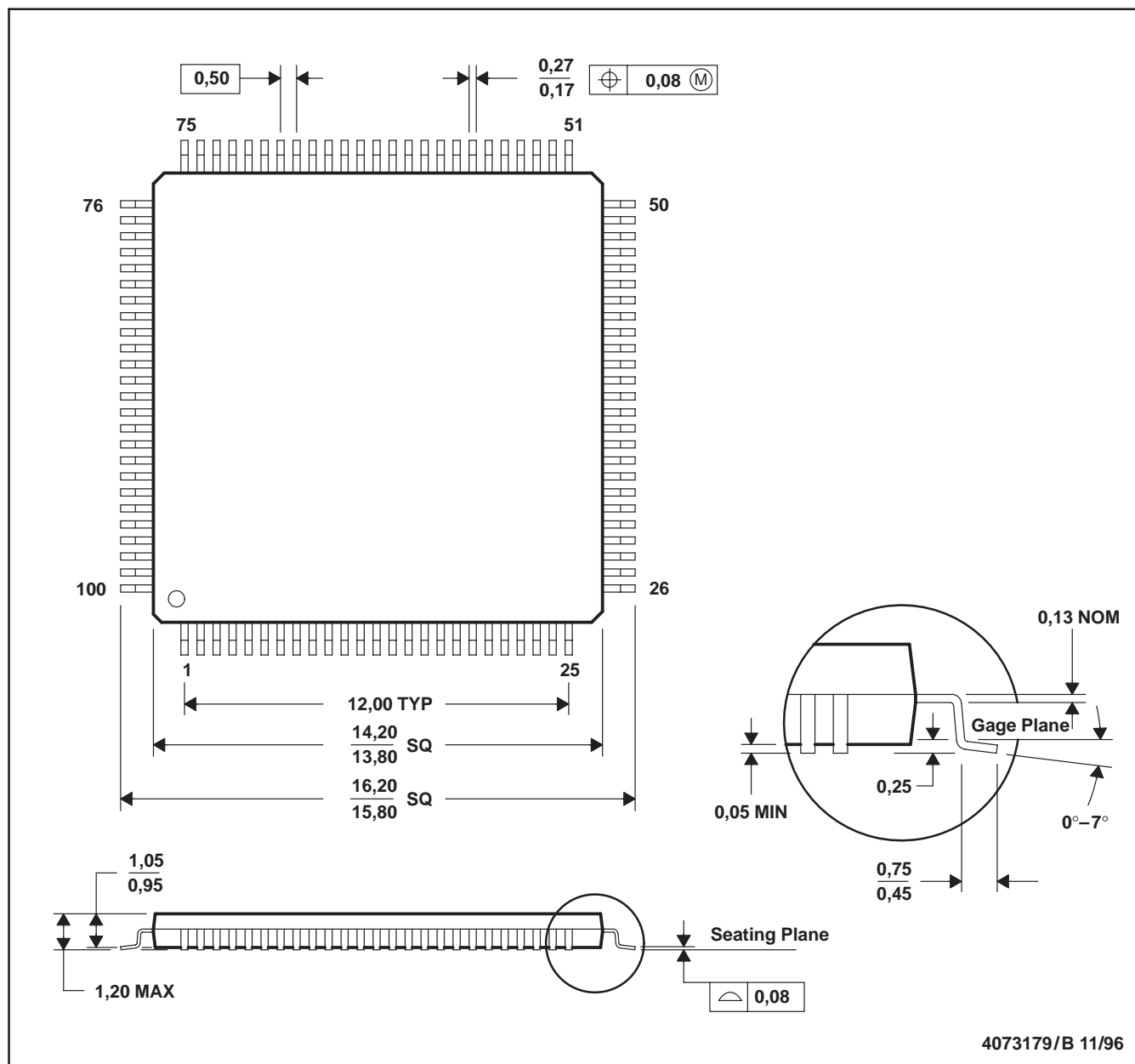
Chamfer on Tray corner indicates Pin 1 orientation of packed units.

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (μm)	P1 (mm)	CL (mm)	CW (mm)
TSB12LV26PZT	PZT	TQFP	100	90	6 X 15	150	315	135.9	7620	15.4	20.3	21
TSB12LV26PZT.A	PZT	TQFP	100	90	6 X 15	150	315	135.9	7620	15.4	20.3	21

PZT (S-PQFP-G100)

PLASTIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-026

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025